

AS1322

Low Voltage, Micropower, DC-DC Step-Up Converters



1 General Description

The AS1322A and the AS1322B are synchronous, fixed frequency, very high-efficiency DC-DC boost converters capable of supplying 3.3V at 150mA from a single AA-supply. Compact size and minimum external parts requirements make these devices perfect for modern portable devices.

High-speed switching frequency (1.2MHz) and internally compensated PWM current mode design provide highly-reliable DC-DC conversion, especially when driving white LEDs.

The converters are available as the standard products listed in [Table 1](#).

Table 1. Standard Products

Model	Light Load Switching
AS1322A	Automatic Powersave Operation
AS1322B	Continuous Switching

The devices contain two internal MOSFET switches: one NMOS switch and one PMOS synchronous rectifier.

Anti-ringing control circuitry reduces EMI by damping the inductor in discontinuous mode, and the devices exhibit extremely low quiescent current ($< 1\mu\text{A}$) in shutdown.

In shutdown mode the battery is connected to the output and V_{OUT} is held at approximately $V_{\text{IN}} - 0.6\text{V}$.

The AS1322 is available in a 6-pin TSOT-23 package.

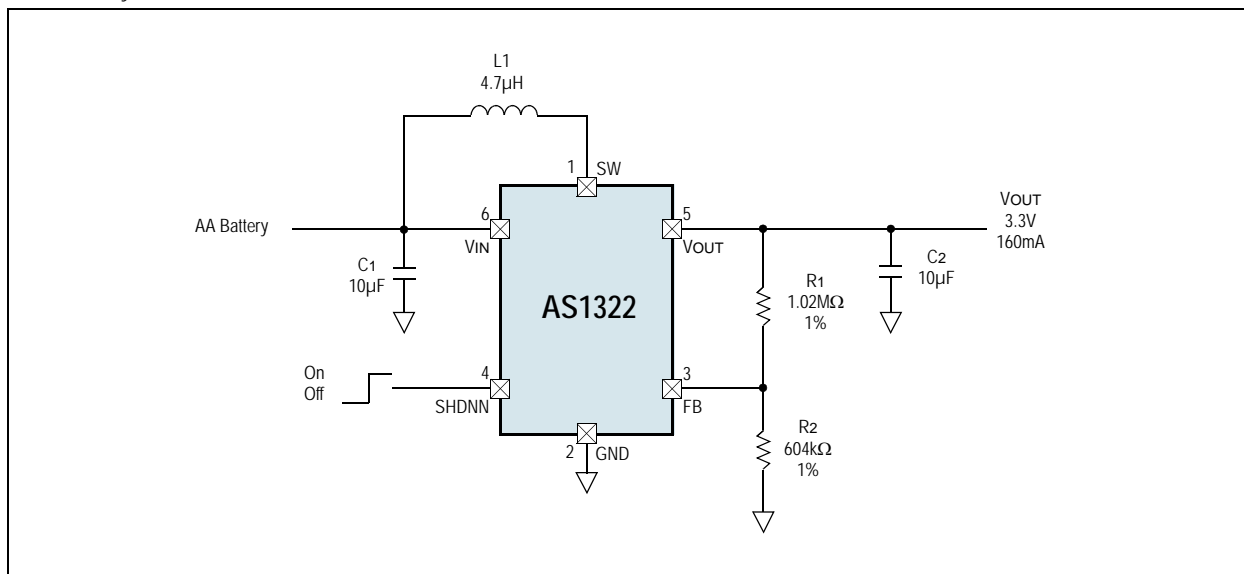
2 Key Features

- 95% Efficiency
- Single-Cell Operation
- Delivers 160mA @ 3.3V (from Single AA Cell)
- Delivers 220mA @ 5.0V (from Two AA Cells)
- Delivers 570mA @ 3.3V (from Two AA Cells)
- Low Start-Up Voltage: 0.85V
- High-Speed Fixed-Frequency: 1.2MHz
- Internal PMOS Synchronous Rectifier
- Automatic Powersave Operation (AS1322A)
- Continuous Switching at Light Loads (AS1322B)
- Anti-Ringing Control Minimizes EMI
- Logic Controlled Shutdown ($< 1\mu\text{A}$)
- Output Range: 2.5 to 5.0V
- 6-pin TSOT-23 Package

3 Applications

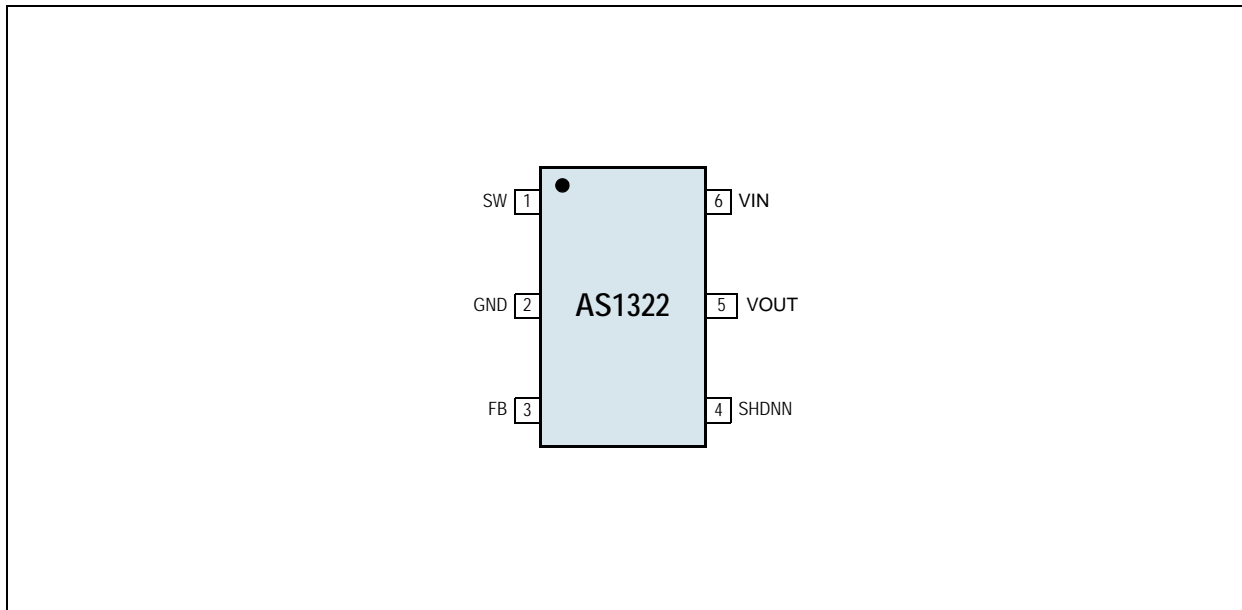
The AS1322 is ideal for low-power applications where ultra-small size is critical as in medical diagnostic equipment, hand-held instruments, pagers, digital cameras, remote wireless transmitters, MP3 players, LCD bias supplies, cordless phones, GPS receivers, and PC cards.

Figure 1. Typical Application Diagram – Single Cell to 3.3V Synchronous Boost Converter



4 Pin Assignments

Figure 2. Pin Assignments (Top View)



4.1 Pin Descriptions

Table 2. Pin Descriptions

Pin Number	Pin Name	Description
1	SW	<p>Switch Pin. Connect an inductor between this pin and VIN. Keep the PCB trace lengths as short and wide as is practical to reduce EMI and voltage overshoot. If the inductor current falls to zero, or pin SHDNN is low, an internal 100Ω anti-ringing switch is connected from this pin to VIN to minimize EMI.</p> <p>Note: An optional Schottky diode can be connected between this pin and VOUT.</p>
2	GND	<p>Signal and Power Ground. Provide a short, direct PCB path between this pin and the negative side of the output capacitor(s).</p>
3	FB	<p>Feedback Pin. Feedback input to the gm error amplifier. Connect a resistor divider tap to this pin. The output voltage can be adjusted from 2.5 to 5V by: $V_{OUT} = 1.23V[1 + (R1/R2)]$</p>
4	SHDNN	<p>Shutdown Pin. Logic controlled shutdown input. 1 = Normal operation, 1.2MHz typical operating frequency. 0 = Shutdown; quiescent current <1μA. If SHDNN is undefined, pin SW may ring.</p> <p>Note: In a typical application, SHDNN should be connected to VIN through a 1MΩ pull-up resistor.</p>
5	VOUT	<p>Output Voltage Sense Input and Drain of the Internal PMOS Synchronous Rectifier. Bias is derived from VOUT when VOUT exceeds VIN. PCB trace length from VOUT to the output filter capacitor(s) should be as short and wide as is practical. VOUT is held at approximately VIN - 0.6V during shutdown.</p>
6	VIN	<p>Input Voltage. The AS1322 gets its start-up bias from VIN unless VOUT exceeds VIN, in which case the bias is derived from VOUT. Thus, once started, operation is completely independent from VIN. Operation is only limited by the output power level and the internal series resistance of the supply.</p>

5 Absolute Maximum Ratings

Stresses beyond those listed in [Table 3](#) may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in [Section 6 Electrical Characteristics on page 4](#) is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 3. Absolute Maximum Ratings

Parameter	Min	Max	Units	Notes
VIN to GND	-0.3	7	V	
SHDNN, SW to GND	-0.3	7	V	
FB to GND	-0.3	5	V	
VOUT	-0.3	7	V	
Operating Temperature Range	-40	+85	°C	
Storage Temperature Range	-65	+125	°C	
Package Body Temperature		+260	°C	The reflow peak soldering temperature (body temperature) specified is in accordance with <i>IPC/JEDEC J-STD-020 "Moisture/Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices"</i> . The lead finish for Pb-free leaded packages is matte tin (100% Sn).

6 Electrical Characteristics

$T_{AMB} = -40$ to $+85^{\circ}\text{C}$, $V_{IN} = +1.2\text{V}$, $V_{OUT} = +3.3\text{V}$, $V_{SHDNN} = +1.2\text{V}$ (unless otherwise specified). Typ values @ $T_{AMB} = +25^{\circ}\text{C}$.

Table 4. Electrical Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Units
	Minimum Start-Up Voltage	$I_{LOAD} = 1\text{mA}$		0.85	1	V
	Minimum Operating Voltage	$SHDNN = V_{IN}$ ¹		0.65	0.85	V
	Output Voltage Adjust Range	$T_{AMB} = 25^{\circ}\text{C}$	2.5		5	V
VFB	Feedback Voltage	$T_{AMB} = T_{MIN}$ to T_{MAX}	1.192	1.23	1.268	V
IFB	Feedback Input Current	$V_{FB} = 1.25\text{V}$ ²		1		nA
IQPWS	Quiescent Current (Powersave Operation)	$V_{FB} = 1.4\text{V}$ ³ , AS1322A only		30	50	μA
IQSHDNN	Quiescent Current (Shutdown)	$V_{SHDNN} = 0\text{V}$		0.01	1	μA
IQ	Quiescent Current (Active)	$V_{FB} = 1.4\text{V}$ ³ , AS1322B only		150	300	μA
INMOSSWL	NMOS Switch Leakage	$V_{SW} = 5\text{V}$		0.1	5	μA
IPMOSSWL	PMOS Switch Leakage	$V_{SW} = 0\text{V}$		0.1	5	μA
RONMOS	NMOS Switch On Resistance	$V_{OUT} = 3.3\text{V}$		0.35	0.8	Ω
		$V_{OUT} = 5\text{V}$		0.20	0.7	
RONPMOS	PMOS Switch On Resistance	$V_{OUT} = 3.3\text{V}$		0.45	0.8	Ω
		$V_{OUT} = 5\text{V}$		0.30	0.7	
INMOS	NMOS Current Limit	$V_{IN} = 2.5\text{V}$		850		mA
IPS	Powersave Operation Current Threshold	AS1322A only ²		3		mA
	Max Duty Cycle	$V_{FB} = 1\text{V}$, $T_{AMB} = T_{MIN}$ to T_{MAX}	80	87		%
fsw	Switching Frequency	$T_{AMB} = 25^{\circ}\text{C}$	0.95	1.2	1.5	MHz
		$T_{AMB} = T_{MIN}$ to T_{MAX}	0.85	1.2	1.5	
VSHDNNH	SHDNN Input High		1			V
VSHDNNL	SHDNN Input Low				0.35	V
ISHDNN	SHDNN Input Current	$V_{SHDNN} = 5.0\text{V}$		0.01	1	μA

1. Minimum V_{IN} operation after start-up is only limited by the battery's ability to provide the necessary power as it enters a deeply discharged state.
2. Specification is guaranteed by design and not 100% production tested.
3. IQPWS is measured at V_{OUT} . Multiply this value by V_{OUT}/V_{IN} to get the equivalent input (battery) current.

Note: All limits are guaranteed. The parameters with min and max values are guaranteed with production tests or SQC (Statistical Quality Control) methods.

7 Typical Operating Characteristics

Figure 3. Powersave mode threshold vs. V_{IN} , $V_{OUT} = 3.0V$

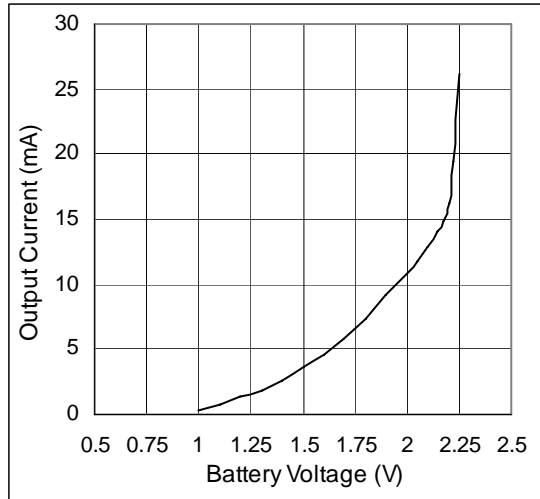


Figure 4. Efficiency vs. Output Current, $V_{OUT} = 3.3V$

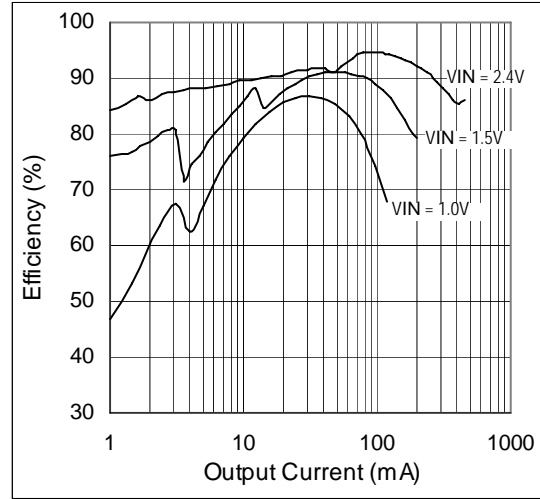


Figure 5. Output Voltage vs. Temperature; $V_{OUT} = 3.3V$, $I_{OUT} = 10mA$

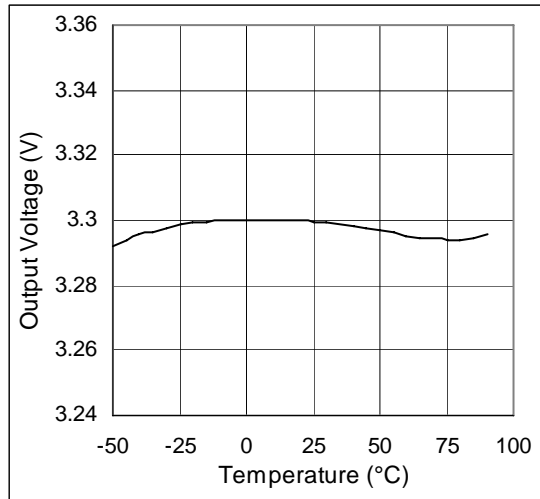


Figure 6. Output Voltage vs. Battery Voltage; $V_{OUT} = 3.3V$, $I_{OUT} = 10mA$

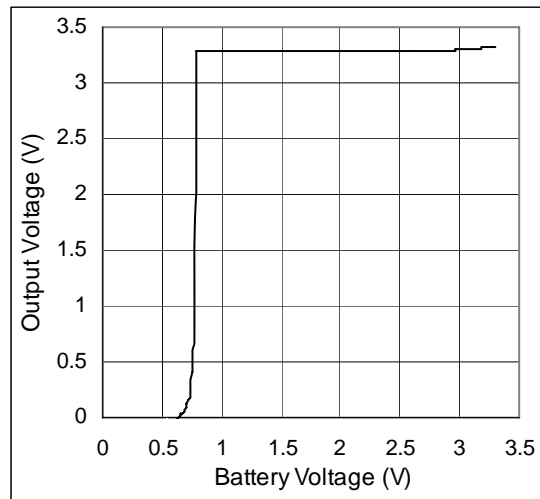


Figure 7. Startup Voltage vs. Output Current;

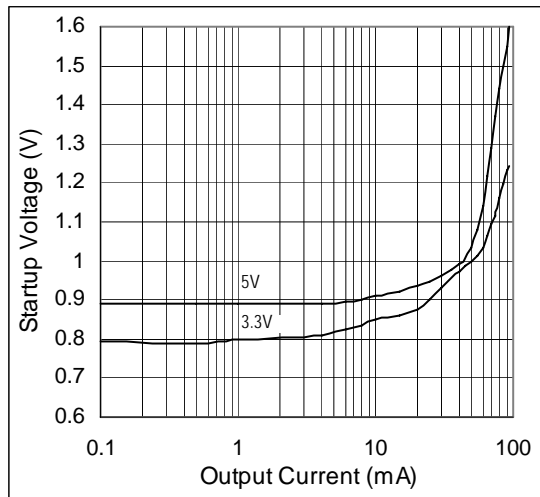


Figure 8. Output Current vs. Battery Voltage; $V_{OUT} = 3.3V$, 3% Tolerance

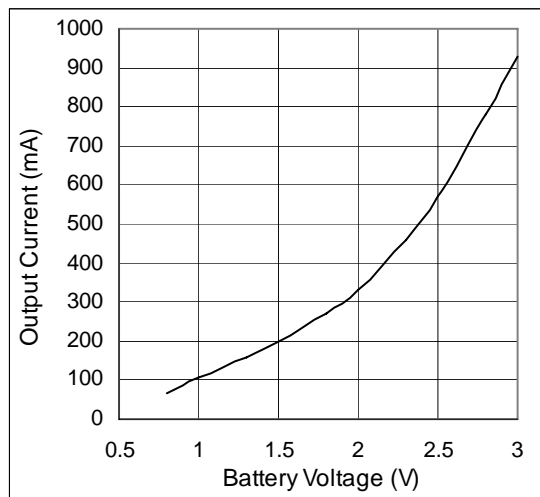


Figure 9. Output Current vs. Battery Voltage;
 $V_{OUT} = 5.0V$, 3% Tolerance $V_{OUT} = 3.3V$, $T_{AMB} = 25^{\circ}C$

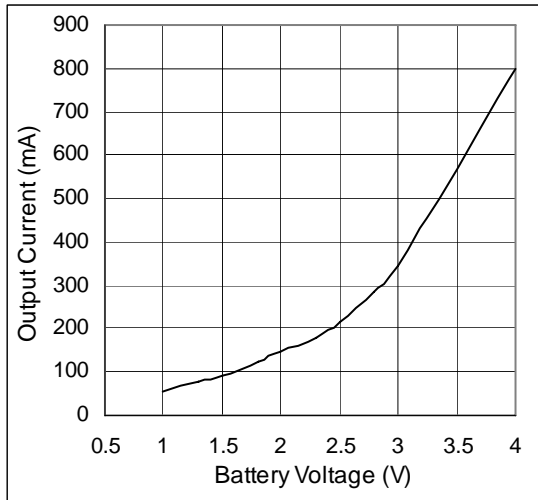


Figure 10. No Load Battery Current vs. V_{BATT}

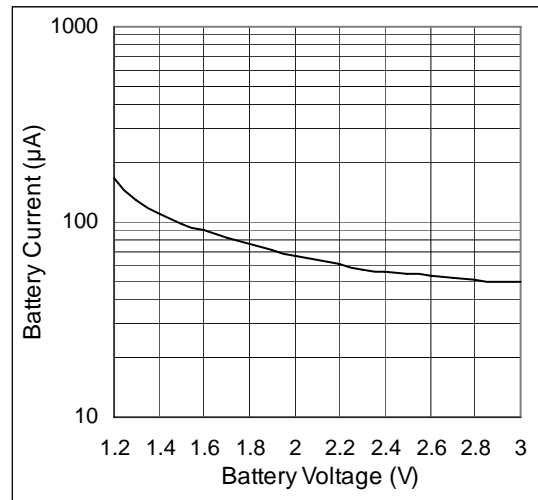


Figure 11. SW Pin Antiringing Operation
 $V_{IN} = 1.3V$, $V_{OUT} = 3.3V$, $L = 10\mu H$, $C = 10\mu F$, $I_{OUT} = 5mA$

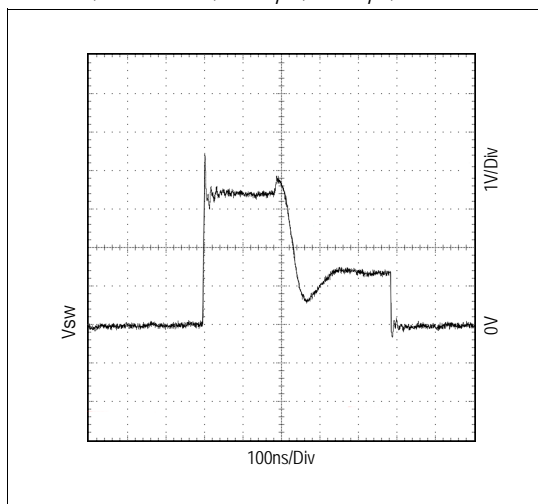


Figure 12. SW Pin Fixed Frequency Continuous Current
 $V_{IN} = 1.3V$, $V_{OUT} = 3.3V$, $L = 10\mu H$, $C = 10\mu F$, $I_{OUT} = 100mA$

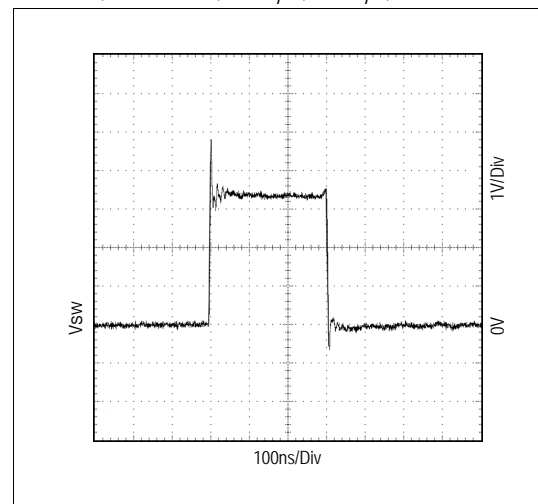


Figure 13. V_{OUT} Transient Response.
 $V_{IN} = 1.3V$, $V_{OUT} = 3.3V$, $L = 10\mu H$, $C = 10\mu F$

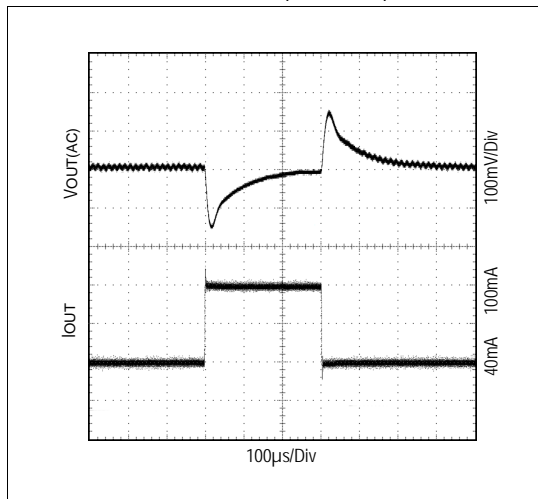
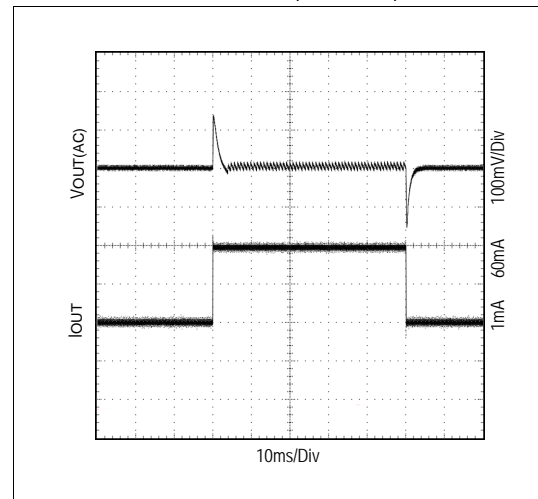


Figure 14. Fixed Frequency vs. Powersave Operation
 $V_{IN} = 1.3V$, $V_{OUT} = 3.3V$, $L = 10\mu H$, $C = 10\mu F$



Parts used for measurements: 10µH (MOS6020-103ML) Inductor, 10µF (GRM31CR70J106KA01L) C_{IN} and C_{OUT}

8.2 Low-Noise Fixed-Frequency Operation

8.2.1 Oscillator

The AS1322 switching frequency is internally fixed at 1.2MHz allowing the use of very small external components.

8.2.2 Error Amplifier

The integrated error amplifier is an internally compensated trans-conductance (g_m) type (current output). The internal 1.23V reference voltage is compared to the voltage at pin FB to generate an error signal at the output of the error amplifier. A voltage divider from V_{OUT} to GND programs the output voltage from 2.5 to 5V via pin FB as:

$$V_{OUT} = 1.23V(1 + (R1/R2)) \quad (EQ 1)$$

8.2.3 Current Sensing

A signal representing the internal NMOS-switch current is summed with the slope compensator. The summed signal is compared to the error amplifier output to provide a peak current control command for the PWM. Peak switch current is limited to approximately 850mA independent of V_{IN} or V_{OUT} .

8.2.4 Zero Current Comparator

The zero current comparator monitors the inductor current to the output and shuts off the PMOS synchronous rectifier once this current drops to 20mA (approx.). This prevents the inductor current from reversing polarity and results in improved converter efficiency at light loads.

8.2.5 Anti-Ringing Control

Anti-ringing control circuitry prevents high-frequency ringing on pin SW as the inductor current approaches zero. This is accomplished by damping the resonant circuit formed by the inductor and the capacitance on pin SW (C_{sw}).

8.3 Powersave Operation (AS1322A)

In light load conditions, the integrated powersave feature removes power from all circuitry not required to monitor V_{OUT} . When V_{OUT} has dropped approximately 1% from nominal, the AS1322A powers up and begins normal PWM operation.

C_{OUT} (see Figure 15 on page 7) recharges, causing the AS1322A to re-enter powersave mode as long as the output load remains below the powersave threshold. The frequency of this intermittent PWM is proportional to load current; i.e., as the load current drops further below the powersave threshold, the AS1322A turns on less frequently. When the load current increases above the powersave threshold, the AS1322A will resume continuous, seamless PWM operation.

Notes:

1. An optional capacitor (C_{FF}) between pins V_{OUT} and FB in some applications can reduce V_{OUTp-p} ripple and input quiescent current during powersave mode. Typical values for C_{FF} range from 15 to 220pF.
2. In powersave mode the AS1322A draws only 30 μ A from the output capacitor(s), greatly improving converter efficiency.

8.4 Shutdown

When pin SHDNN is low the AS1322 is switched off and <1 μ A current is drawn from battery; when pin SHDNN is high the device is switched on. If SHDNN is driven from a logic-level output, the logic high-level (on) should be referenced to V_{OUT} to avoid intermittently switching the device on.

Note: If pin SHDNN is not used, it should be connected directly to pin OUT. V_{OUT} is held at approximately $V_{IN} - 0.6V$ during shutdown.

In shutdown the battery input is connected to the output through the inductor and the internal synchronous rectifier P-FET. Due to the body diode of the internal synchronous rectifier PFET, V_{OUT} is held at approximately $V_{IN} - 0.6V$ during shutdown. This allows the input battery to provide backup power for devices such as an idle microcontroller, memory, or real-time-clock, without the usual diode forward drop. In this way a separate backup battery is not needed.

9 Application Information

The AS1322 is perfectly suited for LED matrix displays, bar-graph displays, instrument-panel meters, dot matrix displays, set-top boxes, white goods, professional audio equipment, medical equipment, industrial controllers to name a few applications.

Along with [Figure 1 on page 1](#), Figures 16-19 depict a few of the many applications for which the AS1322 converters are perfectly suited.

Figure 16. Single AA Cell to 3.3V Synchronous Boost Converter with Load Disconnect in Shutdown

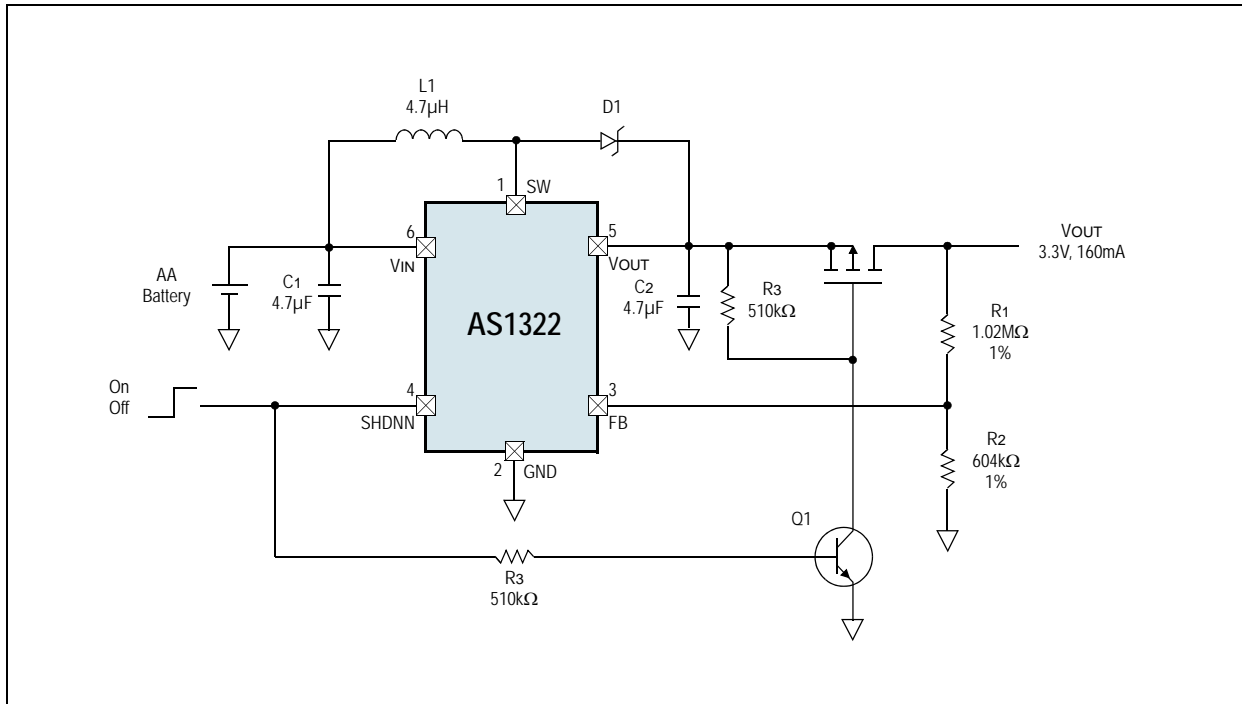


Figure 17. Single Lithium Cell to 5V, 250mA

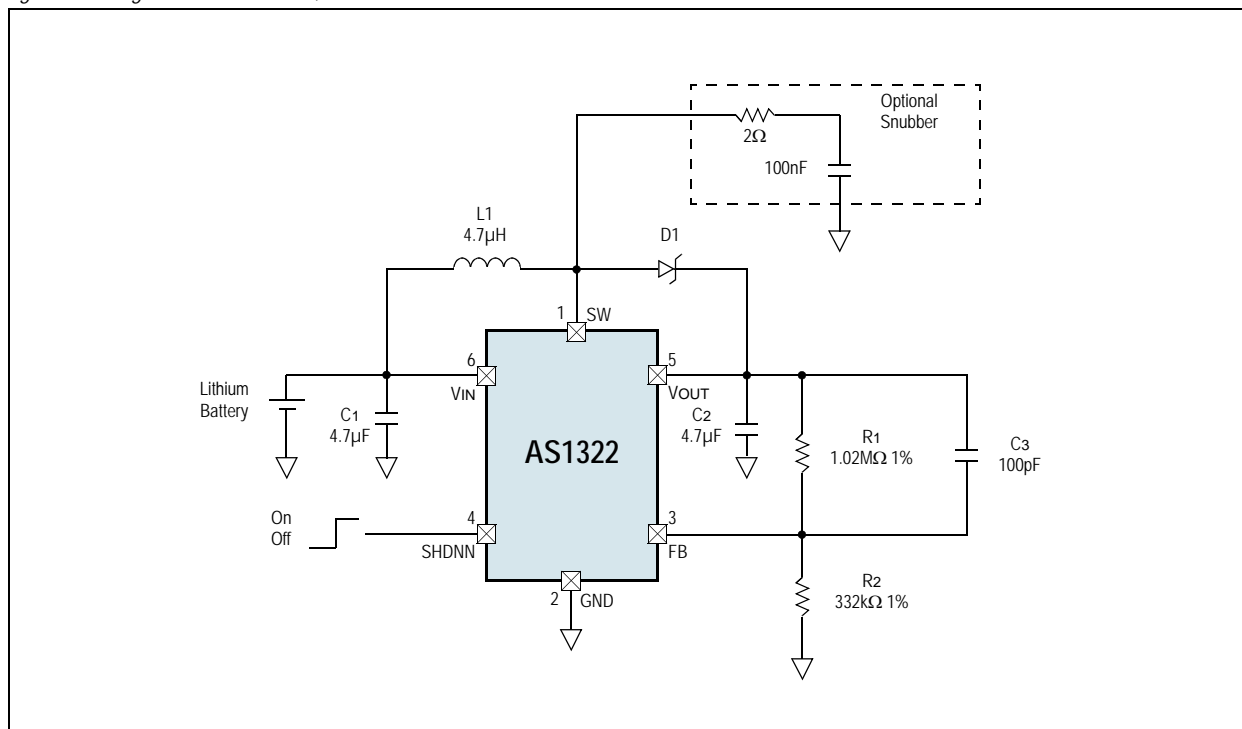


Figure 18. Single AA Cell to $\pm 3V$ Synchronous Boost Converter

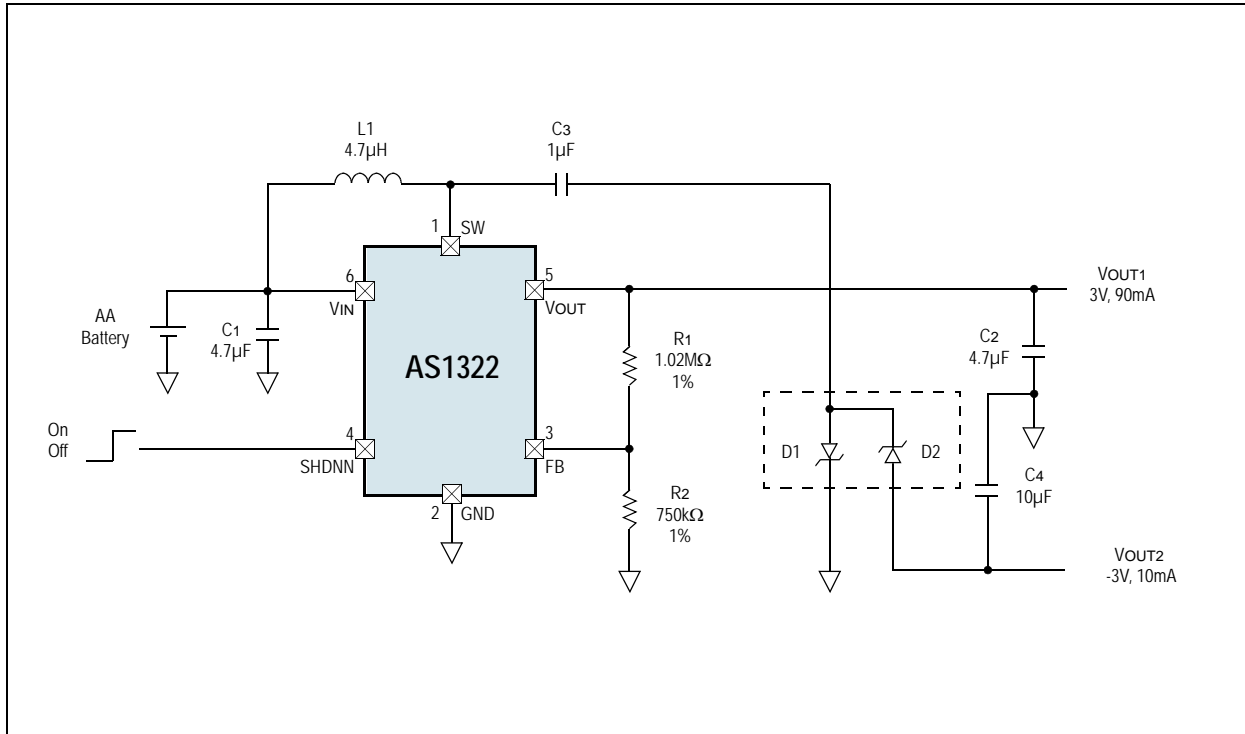
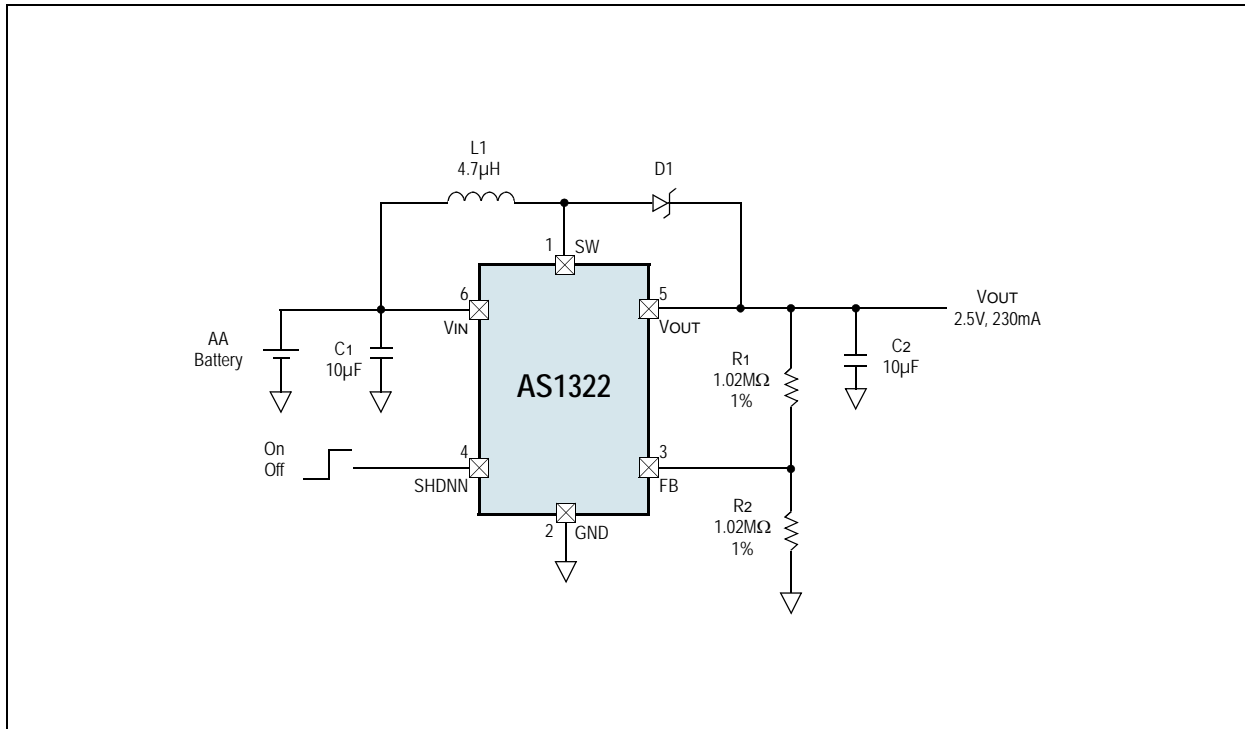


Figure 19. Single AA Cell to 2.5V Synchronous Boost Converter

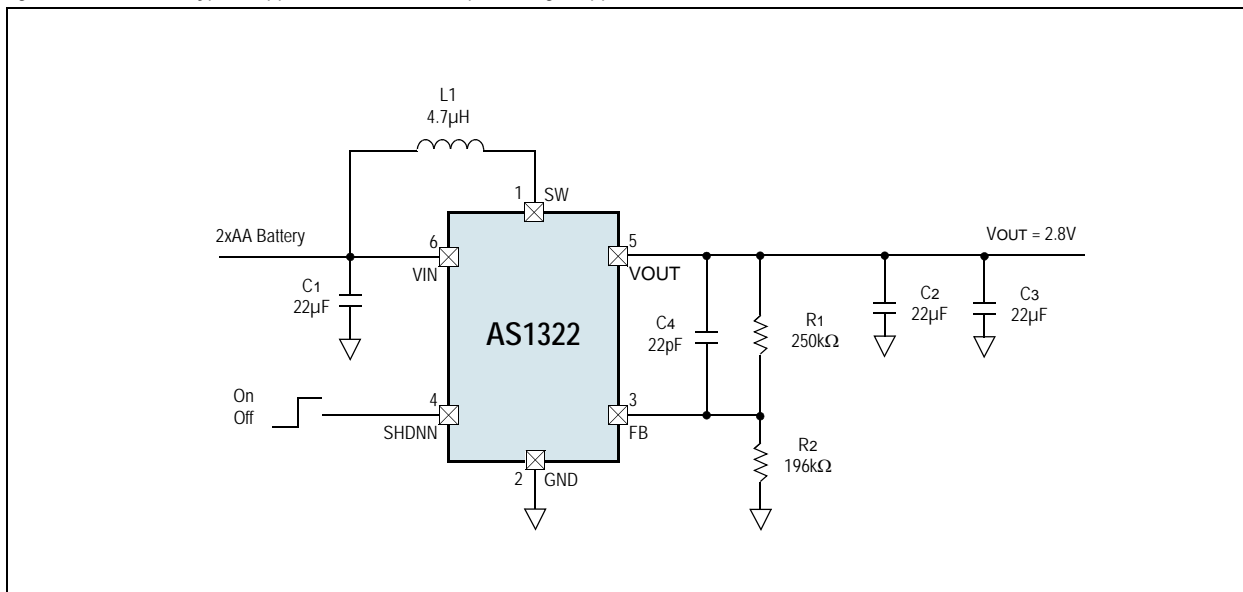


9.1 Output Voltage Ripple

The AS1322 is designed to work at high efficiency. In order to reduce the output ripple the following improvements are recommended:

- Use a higher output capacitor, up to $44\mu\text{F}$ and a higher input capacitor ($22\mu\text{F}$).
- Use smaller values for the resistor divider. R1 should be about $300\text{k}\Omega$. To avoid a high leakage current from pin VOUT through the resistor divider to GND, R1 should not be less than $100\text{k}\Omega$.
- To reduce the output ripple it's also possible to speed up the feedback loop. To achieve this, place a 22pF (C4 in Figure 20) capacitor in parallel to R1. Via C4 the fast transients are shorted to the FB pin and the feedback loop is even faster. A $1\text{M}\Omega$ resistor for R1 slows down the FB loop.
- Due to noise and to their non linear behavior, the use of potentiometers is not recommended.

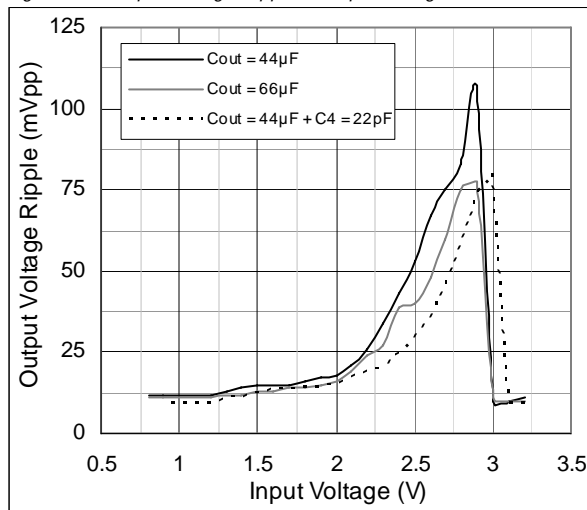
Figure 20. AS1322 - Typical Application for lower Output Voltage Ripple



Note: For correct measurements of the output ripple connect the oscilloscope probe as close as possible to the positive plate of the C_{OUT} and connect the GND of the oscilloscope probe to the negative plate of the C_{OUT}. This will reduce the inductive coupling and will deliver a more accurate measurement result.

The output ripple is getting higher as V_{IN} is getting closer to V_{OUT}. Figure 21 shows that the above mentioned improvements reduce the output voltage ripple. If V_{IN} is higher than V_{OUT} the AS1322 stops switching and V_{IN} is connected to V_{OUT} via the inductor and the internal P-FET.

Figure 21. Output Voltage Ripple vs. Input Voltage; V_{OUT} = 2.8V, I_{OUT} = 0.8mA



9.2 External Component Selection

9.2.1 Inductor Selection

The fast switching frequency (1.2MHz) of the AS1322 allows for the use of small surface mount or chip inductor for the external inductor (see Figure 15 on page 7).

The required minimum values for the external inductor are:

- 3.3μH for applications ≤ 3.6V
- 4.7μH for applications > 3.6V

Larger inductor values allow greater output current capability by reducing the inductor ripple current. Increasing the inductance above 10μH will increase size while providing negligible improvement in output current capability.

The approximate output current capability of the AS1322 versus inductor value is given in:

$$I_{OUT(MAX)} = \eta \cdot \left(I_P - \frac{V_{IN} \cdot D}{f \cdot L \cdot 2} \right) \cdot (1 - D) \quad (EQ 2)$$

Where:

η is the estimated efficiency;

I_P is the peak current limit value (0.6A);

V_{IN} is the input voltage;

D is the steady-state duty ratio = $(V_{OUT} - V_{IN})/V_{OUT}$;

f is the switching frequency (1.2MHz typ);

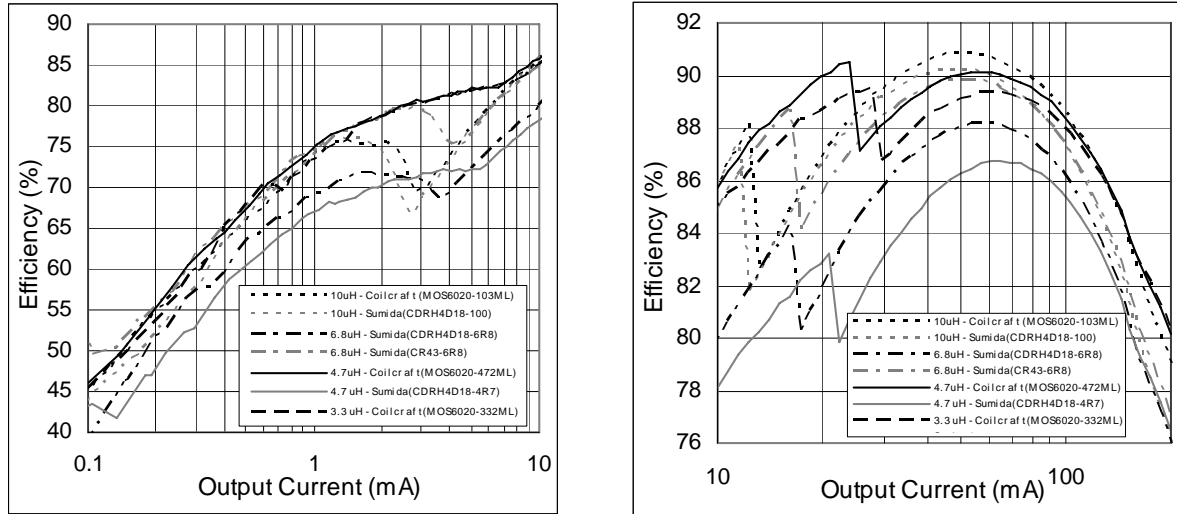
L is the inductor value.

The inductor current ripple is typically set for 20 to 40% of the maximum inductor current (I_P). High-frequency ferrite core inductor materials reduce frequency dependent power losses compared to less expensive powdered iron types, which result in improved converter efficiency.

The inductor should have low ESR to reduce the I^2R power losses, and must be able to handle the peak inductor current without saturating. Molded chokes and some chip inductors normally do not have enough core to support the peak inductor currents of the AS1322 (850mA typ). To minimize radiated noise, use a toroid, pot core, or shielded bobbin inductor.

Table 5. Recommended Inductors

Part Number	L	DCR	Current Rating	Dimensions (L/W/T)	Manufacturer
MOS6020-103ML	10μH	93mΩ	1A	6.8x6.0x2.4mm	Coilcraft www.coilcraft.com
MOS6020-472ML	4.7μH	50mΩ	1.5A	6.8x6.0x2.4mm	
MOS6020-332ML	3.3μH	46mΩ	1.8A	6.8x6.0x2.4mm	
CDRH4D18-100	10μH	200mΩ	0.61A	6.9x5.0x2.0mm	Sumida www.sumida.com
CDRH4D18-6R8	6.8μH	200mΩ	0.76A	6.9x5.0x2.0mm	
CR43-6R8	6.8μH	131.2mΩ	0.95A	4.8x4.3x3.5mm	
CDRH4D18-4R7	4.7μH	162mΩ	0.84A	6.9x5.0x2.0mm	

Figure 22. Efficiency Comparison of Different Inductors, $V_{IN} = 1.5V$, $V_{OUT} = 3.3V$ 

9.2.2 Output Capacitor Selection

Low ESR capacitors should be used to minimize V_{OUT} ripple. Multi-layer ceramic capacitors are recommended since they have extremely low ESR and are available in small footprints. A 2.2 to 10 μ F output capacitor is sufficient for most applications. Larger values up to 22 μ F may be used to obtain extremely low output voltage ripple and improve transient response.

An additional phase lead capacitor may be required with output capacitors larger than 10 μ F to maintain acceptable phase margin. X5R and X7R dielectric materials are recommended due to their ability to maintain capacitance over wide voltage and temperature ranges.

Table 6. Recommended Output Capacitor

Part Number	C	TC Code	Rated Voltage	Dimensions (L/W/T)	Manufacturer
JMK212BJ226MG-T	22 μ F \pm 20%	X5R	6.3V	2x1.3x1.3mm	Taiyo Yuden www.t-yuden.com

Input Capacitor Selection. Low ESR input capacitors reduce input switching noise and reduce the peak current drawn from the battery. Ceramic capacitors are recommended for input decoupling and should be located as close to the device as is practical. A 4.7 μ F input capacitor is sufficient for most applications. Larger values may be used without limitations.

Table 7. Recommended Input Capacitor

Part Number	C	TC Code	Rated Voltage	Dimensions (L/W/T)	Manufacturer
GRM31CR70J106KA01L	10 μ F \pm 10%	X7R	6.3V	3.2x1.6x1.6mm	Murata www.murata.com

Diode Selection. A Schottky diode should be used to carry the output current for the time it takes the PMOS synchronous rectifier to switch on. For $V_{OUT} < 4.5V$ a Schottky diode is optional, although using one will increase device efficiency by 2 to 3%.

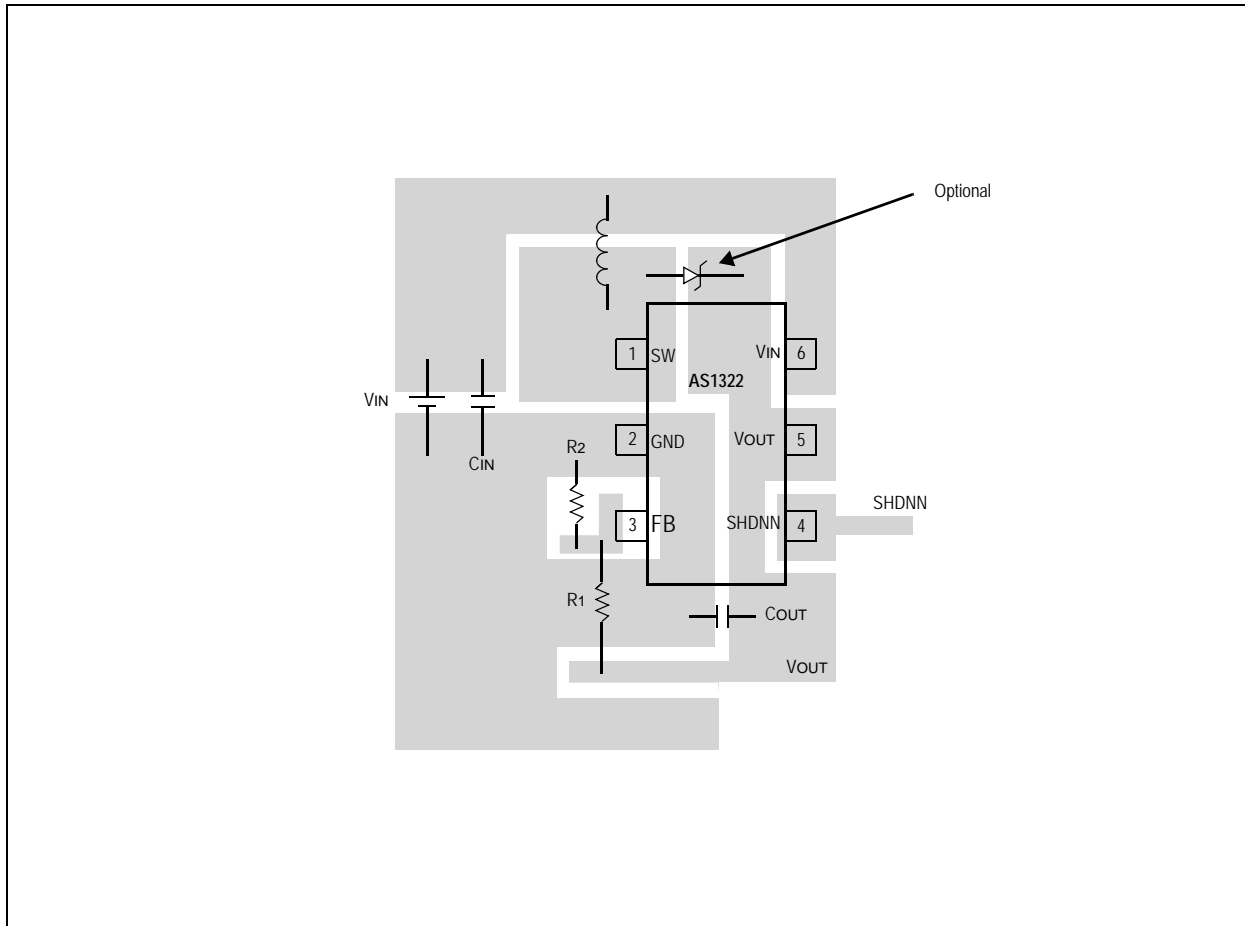
Note: Do not use ordinary rectifier diodes, since the slow recovery times will compromise efficiency.

9.3 PCB Layout Guidelines

The high-speed operation of the AS1322 requires proper layout for optimum performance. Figure 23 shows the recommended component layout.

- A large ground pin copper area will help to lower the device temperature.
- A multi-layer board with a separate ground plane is recommended.
- Traces carrying large currents should be direct.
- Trace area at pin FB should be as small as is practical.
- The lead-length to the battery should be as short as is practical.

Figure 23. Recommended Single-Layer Component Placement



Symbol	Min	Typ	Max	Notes
A			1.00	
A1	0.01	0.05	0.10	
A2	0.84	0.87	0.90	
b	0.30		0.45	6,7
b1	0.31	0.35	0.39	6,7
c	0.12	0.15	0.20	6
c1	0.08	0.13	0.16	6
D	2.90BSC			3,4
E	2.80BSC			3,4
E1	1.60BSC			3,4

Symbol	Min	Typ	Max	Notes
e	0.95BSC			
e1	1.90BSC			
L	0.30	0.40	0.50	
L1	0.60REF			
L2	0.25BSC			
N		6		
R	0.10			
R1	0.10		0.25	
θ	0°	4°	8°	
$\theta 1$	4°	10°	12°	

Tolerances of Form and Position				
aaa		0.15		1,2
bbb		0.25		1,2
ccc		0.10		1,2
ddd		0.20		1,2

Notes:

1. Dimensioning and tolerancing conform to *ASME Y14.5M - 1994*.
2. Dimensions are in millimeters.
3. Dimension D does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, and gate burrs shall not exceed 0.15mm per end. Dimension E1 does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.15mm per side. Dimensions D and E1 are determined at datum H.
4. The package top can be smaller than the package bottom. Dimensions D and E1 are determined at the outermost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs, and interlead flash, but include any mismatches between the top of the package body and the bottom. D and E1 are determined at datum H.
5. Datums A and B are to be determined at datum H.
6. These dimensions apply to the flat section of the lead between 0.08 and 0.15mm from the lead tip.
7. Dimension b does not include dambar protrusion. Allowable dambar protrusion shall be 0.08mm total in excess of the b dimension at the maximum material condition. The dambar cannot be located on the lower radius of the foot. Minimum space between the protrusion and an adjacent lead shall not be less than 0.77mm.

11 Ordering Information

The device is available as the standard products listed in [Table 8](#).

Table 8. Ordering Information

Ordering Code	Marking	Description	Delivery Form	Package
AS1322A-BTTT	ASKQ	Low Voltage, Micropower, DC-DC Step-Up Converter with Automatic Powersave Operation	Tape and Reel	6-pin TSOT-23
AS1322B-BTTT	ASKZ	Low Voltage, Micropower, DC-DC Step-Up Converter with Continuous Switching	Tape and Reel	6-pin TSOT-23

Note: All products are RoHS compliant.

Buy our products or get free samples online at ICdirect: <http://www.austriamicrosystems.com/ICdirect>

Technical Support is found at <http://www.austriamicrosystems.com/Technical-Support>

For further information and requests, please contact us <mailto:sales@austriamicrosystems.com> or find your local distributor at <http://www.austriamicrosystems.com/distributor>

Design the AS1322 online at <http://www.austriamicrosystems.com/analogbench>
[analogbench](#) is a powerful design and simulation support tool that operates in on-line and off-line mode to evaluate performance and generate application-specific bill-of-materials for austriamicrosystems' power management devices.



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Contact Information

Headquarters

austriamicrosystems AG
Tobelbaderstrasse 30
A-8141 Unterpremstaetten, Austria

Tel: +43 (0) 3136 500 0
Fax: +43 (0) 3136 525 01

For Sales Offices, Distributors and Representatives, please visit:

<http://www.austriamicrosystems.com/contact>